

## Process Change Notice

**Parts Affected:**

Chip process CPZ19, Zener Diode discrete semiconductors, wafers, and die in chip form.

**Extent of Change:**

An overall reduction of the die area.

The CPZ19 chip process currently measures 17.7 x 17.7 mils and is being replaced by the CPZ28 chip process which measures 13 x 13 mils.

**Reason for Change:**

To accommodate assemblies of extremely small surface mount, epoxy molded packages.

**Effect of Change:**

This change does not affect the electrical characteristics of any device.

**Effective Date of Change:**

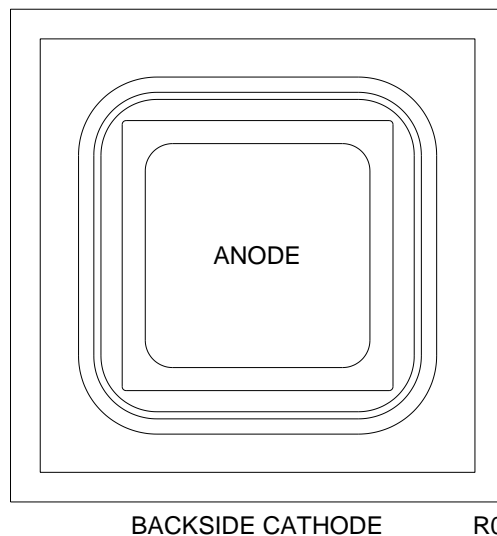
Existing inventory will be shipped until depleted.

**Sample Availability:**

Please contact Salesperson or Manufacturer's Representative.

**Figures:**

**CPZ28 Chip Geometry**



Die Size: 13 x 13 mils  
Die Thickness: 7.8 mils  
Bond Pad Area (Anode): 7.0 x 7.0 mils

**Part Numbers Affected:**

CPZ19-CMPZ5235B-CT thru CPZ19-CMPZ5261B-CT  
CMPZ5235B thru CMPZ5261B

CPZ19-BZX84C6V8-CT thru CPZ19-BZX84C47-CT  
BZX84C6V8 thru BZX84C47

CMDZ5235B thru CMDZ5261B  
CMSZ5235B thru CMSZ5261B  
CMHZ5235B thru CMHZ5261B  
CMKZ5235B thru CMKZ5261B

CMPZDA6V8 thru CMPZDA47V  
CMSZDA6V8 thru CMSZDA47V  
CMDZ6V8 thru CMDZ47V  
CMOZ6V8 thru CMOZ47V  
CMOZ6L8 thru CMOZ47L  
CMDZ6L8 thru CMDZ47L

CMXZ6V8TO thru CMXZ47VTO

CMPZ4692 thru CMPZ4717  
CMHZ4692 thru CMHZ4717  
CMHZ4099 thru CMHZ4125